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March 2013

# FSUSB40 — Low-Power, Two-Port, Hi-Speed, USB2.0 (480Mbps) Switch

### **Features**

- Low On Capacitance: 5.9pF Typical
   Low On Resistance: 3.9Ω Typical
- Low Power Consumption: 1µA Maximum
  - 15μA Maximum I<sub>CCT</sub> over an Expanded Voltage Range (V<sub>IN</sub>=1.8V, V<sub>CC</sub>=4.3V)
- Wide -3db Bandwidth: > 720MHz
- Packaged in:
  - 10-Lead MicroPak™ (1.6 x 2.1mm)
  - 10-Lead UMLP (1.4 x 1.8mm)
- 8kV ESD Rating, >16kV Power/GND ESD Rating
- Power-Off Protection on All Ports When V<sub>CC</sub>=0V
  - D+/D- Pins Tolerate up to 5.25V
- Over-Voltage Tolerance (OVT) on all USB Ports Up to 5.25V without External Components

### **Applications**

- Cell phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-Top Box

### **IMPORTANT NOTE:**

For additional performance information, please contact analogswitch@fairchildsemi.com.

# **Description**

The FSUSB40 is a bi-directional, low-power, two-port, Hi-Speed, USB2.0 switch. Configured as a double-pole, double-throw switch (DPDT) switch, it is optimized for switching between two Hi-Speed (480Mbps) sources or a Hi-Speed and Full-Speed (12Mbps) source.

The FSUSB40 is compatible with the requirements of USB2.0 and features an extremely low on capacitance  $(C_{ON})$  of 5.9pF. The wide bandwidth of this device (720MHz) exceeds the bandwidth needed to pass the third harmonic, resulting in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk also minimizes interference.

The FSUSB40 contains special circuitry on the switch I/O pins for applications where the  $V_{\rm CC}$  supply is powered-off ( $V_{\rm CC}$ =0), which allows the device to withstand an over-voltage condition. This device is designed to minimize current consumption even when the control voltage applied to the SEL pin is lower than the supply voltage ( $V_{\rm CC}$ ). This feature is especially valuable to ultra-portable applications, such as cell phones, allowing for direct interface with the general-purpose I/Os of the baseband processor. Other applications include switching and connector sharing in portable cell phones, PDAs, digital cameras, printers, and notebook computers.

# **Ordering Information**

Part Number	Top Mark	Operating Temperature Range	© Eco Status	Package
FSUSB40L10X	HD	-40 to +85°C	RoHS	10-Lead MicroPak™ 1.6 x 2.1mm, JEDEC MO-255B
FSUSB40UMX	НС	-40 to +85°C	Green	10-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 1.4 x 1.8mm

MicroPak™ is a trademark of Fairchild Semiconductor Corporation.

For Fairchild's definition of Eco Status, please visit: <a href="http://www.fairchildsemi.com/company/green/rohs\_green.html">http://www.fairchildsemi.com/company/green/rohs\_green.html</a>.

# **Analog Symbol**

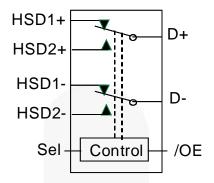


Figure 1. Analog Symbol

# **Pin Assignments**

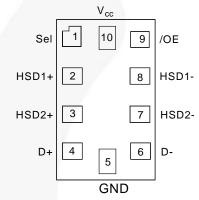


Figure 2. Pad Assignments for MicroPak™ (Top Through View)

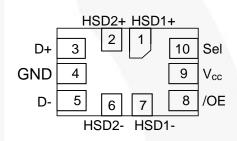


Figure 3. Pin Assignments for UMLP (Top Through View)

# **Pin Definitions**

MicroPak™ Pin#	UMLP Pin #	Name	Description
9	8	/OE	Switch Enable
1	10	Sel	Switch Select
4, 6	3, 5	D+, D-	USB Data Bus
2, 3, 7, 8	1, 2, 6, 7	HSDn+, HSDn-	Multiplexed Source inputs
5	4	GND	Ground

# **Truth Table**

Sel	/OE	Function
X	Н	Disconnect
L	L	D+, D-=HSD1+, HSD1-
Н	L	D+, D-=HSD2+, HSD2-

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage		-0.5	+5.5	V
V <sub>CNTRL</sub>	DC Input Voltage (S, /OE) <sup>(1)</sup>		-0.5	V <sub>CC</sub>	V
V <sub>SW</sub>	DC Switch I/O Voltage <sup>(1)</sup>		-0.50	5.25	V
I <sub>IK</sub>	DC Input Diode Current		-50		mA
I <sub>OUT</sub>	DC Output Current			100	mA
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
		All Pins		7	
ESD	Human Body Model, JEDEC: JESD22-A114	I/O to GND	/	8	kV
LOD		Power to GND		16	I.V
	Charged Device Model, JEDEC: JESD22-C10	01	1	2	

### Note:

 The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
$V_{CC}$	Supply Voltage	3.0	4.3	V
$V_{CNTRL}$	Control Input Voltage (S, /OE) <sup>(2)</sup>	0	V <sub>CC</sub>	V
$V_{SW}$	Switch I/O Voltage	-0.5	4.5	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C

### Note:

2. The control input must be held HIGH or LOW and it must not float.

# **DC Electrical Characteristics**

All typical value are at 25°C unless otherwise specified.

Coursels al	Doromotor	Conditions	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	T <sub>A</sub> =- 40°C to +85°C			Units
Symbol	Parameter	Conditions	V <sub>cc</sub> (V)	Min.	Тур.	Max.	Units
V <sub>IK</sub>	Clamp Diode Voltage	I <sub>IN</sub> =-18mA	3.0			-1.2	V
V <sub>IH</sub>	Input Voltage High		3.0 to 3.6	1.3			٧
VIH	input voltage riigii		4.3	1.7			V
V <sub>IL</sub>	Input Voltage Low		3.0 to 3.6			0.5	V
VIL	input voltage Low		4.3			0.7	V
I <sub>IN</sub>	Control Input Leakage	$V_{SW}$ =0 to $V_{CC}$	4.3	-1		1	μΑ
I <sub>OZ</sub>	Off State Leakage	0 ≤ Dn, HSD1n, HSD2n ≤ 3.6V	4.3	-2		2	μA
I <sub>OFF</sub>	Power-Off Leakage Current (All I/O Ports)	V <sub>SW</sub> =0V to 4.3V, V <sub>CC</sub> =0V Figure 5	0	-2		2	μΑ
R <sub>ON</sub>	HS Switch On Resistance <sup>(3)</sup>	V <sub>SW</sub> =0.4V, I <sub>ON</sub> =-8mA Figure 4	3.0		3.9	6.5	Ω
$\Delta R_{ON}$	HS Delta Ron <sup>(4)</sup>	V <sub>SW</sub> =0.4V, I <sub>ON</sub> =-8mA	3.0		0.65		Ω
$I_{CC}$	Quiescent Supply Current	V <sub>CNTRL</sub> =0 or Vcc, I <sub>OUT</sub> =0	4.3			1.0	μΑ
	Increase in I <sub>CC</sub> Current Per	V <sub>CNTRL</sub> =2.6V V <sub>CC</sub> =4.3V	4.3	1		10.0	μA
I <sub>CCT</sub>	Control Voltage and V <sub>CC</sub>	V <sub>CNTRL</sub> =1.8V V <sub>CC</sub> =4.3V	4.3		V.	15.0	μΑ

### **Notes**

- 3. Measured by the voltage drop between HSDn and Dn pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (HSDn or Dn ports).
- 4. Guaranteed by characterization.

# **AC Electrical Characteristics**

All typical value are for  $V_{\text{CC}}$ =3.3V at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	V (V)	T <sub>A</sub> =- 4	40ºC to	+85ºC	l Inito
Symbol	Parameter Conditions v <sub>CC</sub> (v)		V <sub>CC</sub> (V)	Min.	Тур.	Max.	Units
t <sub>ON</sub>	Turn-On Time S, /OE to Output	$R_L$ =50 $\Omega$ , $C_L$ =5pF $V_{SW}$ =0.8V Figure 6, Figure 7	3.0 to 3.6		13	30	ns
t <sub>OFF</sub>	Turn-Off Time S, /OE to Output	$R_L$ =50 $\Omega$ , $C_L$ =5pF $V_{SW}$ =0.8V Figure 6, Figure 7	3.0 to 3.6		12	25	ns
t <sub>PD</sub>	Propagation Delay <sup>(5)</sup>	$C_L$ =5 pF, $R_L$ =50 $\Omega$ Figure 6, Figure 8	3.3		0.25		ns
t <sub>BBM</sub>	Break-Before-Make	$R_L$ =50 $\Omega$ , $C_L$ =5pF $V_{SW1}$ = $V_{SW2}$ =0.8V Figure 12	3.0 to 3.6	2.0		6.5	ns
O <sub>IRR</sub>	Off Isolation	R <sub>L</sub> =50Ω, f=240MHz Figure 14	3.0 to 3.6		-30		dB
Xtalk	Non-Adjacent Channel Crosstalk	R <sub>L</sub> =50Ω, f=240MHz Figure 15	3.0 to 3.6		-45		dB
BW	-3db Bandwidth	$R_L$ =50 $\Omega$ , $C_L$ =0pF Figure 13	3.0 to 3.6		720		MHz
BVV	-Sub Balluwidti	$R_L$ =50 $\Omega$ , $C_L$ =5pF Figure 13	3.0 10 3.0		550		MHz

### Note:

# **USB Hi-Speed-Related AC Electrical Characteristics**

Symbol	Darameter	Conditions	V 00	T <sub>A</sub> =- 40°C to +85°C			l luite
Symbol	Parameter	Conditions	V <sub>cc</sub> (V)	Min.	Тур.	Max.	Units
t <sub>SK(P)</sub>	Skew of Opposite Transitions of the Same Output <sup>(6)</sup>	$C_L=5pF, R_L=50\Omega$ Figure 9	3.0 to 3.6	/	20		ps
tJ	Total Jitter <sup>(6)</sup>	$R_L=50\Omega$ , $C_L=5pf$ , $t_R=t_F=500ps$ (10-90%) at 480Mbps $(PRBS=2^{15}-1)$	3.0 to 3.6		200		ps

### Note:

# Capacitance

Symbol	Parameter	Conditions	T <sub>A</sub> =- 40°C to +85°C			Units
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Ullits
C <sub>IN</sub>	Control Pin Input Capacitance	V <sub>CC</sub> =0V		1.5		
C <sub>ON</sub>	D+/D- On Capacitance	V <sub>CC</sub> =3.3V, /OE=0V, f=1MHz Figure 11		5.9	6.5	pF
C <sub>OFF</sub>	D1n, D2n Off Capacitance	V <sub>CC</sub> and /OE=3.3V Figure 10		2.0		

<sup>5.</sup> Guaranteed by characterization.

<sup>6.</sup> Guaranteed by characterization.

# **Test Diagrams**

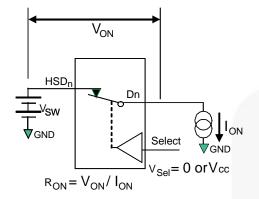
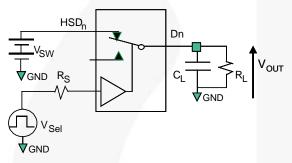


Figure 4. On Resistance



 $R_L$ ,  $R_S$ , and  $C_L$  are functions of the application environment (see AC Tables for specific values)  $C_L$  includes test fixture and stray capacitance.

Figure 6. AC Test Circuit Load

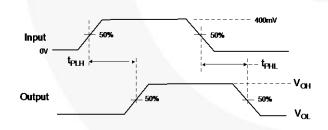


Figure 8. Propagation Delay (t<sub>R</sub>t<sub>F</sub> - 500ps)

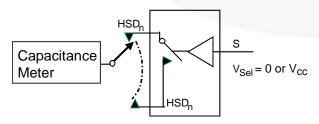
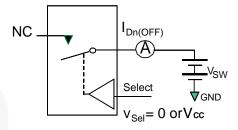


Figure 10. Channel Off Capacitance



\*\*Each switch port is tested separately

Figure 5. Off Leakage

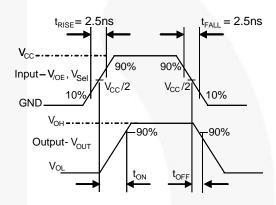


Figure 7. Turn-On / Turn-Off Waveforms

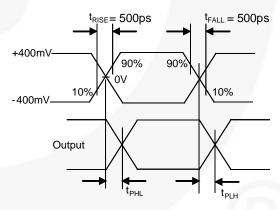


Figure 9. Intra-Pair Skew Test t<sub>SK(P)</sub>

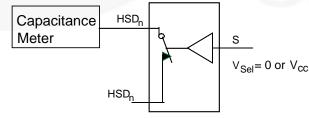


Figure 11. Channel On Capacitance

# Test Diagrams (Continued)

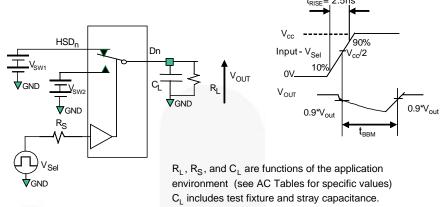


Figure 12. Break-Before-Make Interval Timing

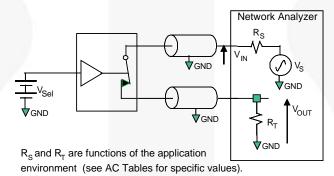
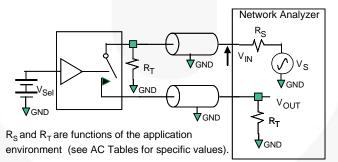


Figure 13. Bandwidth



Off isolation = 20 Log  $(V_{OUT} / V_{IN})$ 

Figure 14. Channel Off Isolation

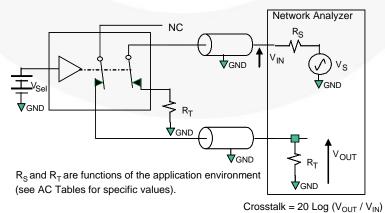


Figure 15. Non-Adjacent Channel-to-Channel Crosstalk

# **Physical Dimensions**

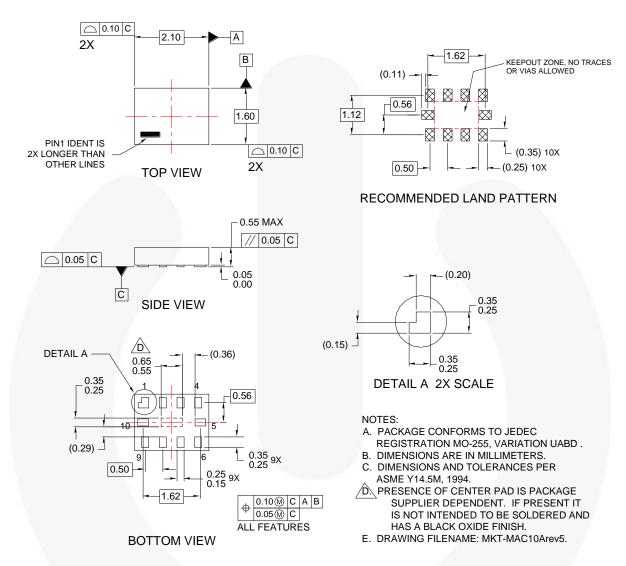
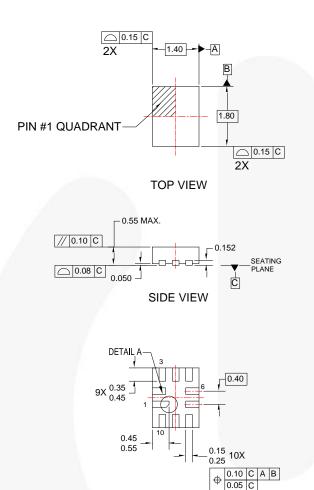


Figure 16. 10-Lead MicroPak™

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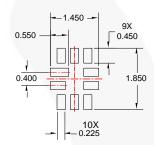
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# **Physical Dimensions**

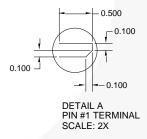


0.663 9X 0.563 0.400 2.100 0.400 10X 0.225

### RECOMMENDED LAND PATTERN



OPTIONAL MINIMIAL TOE LAND PATTERN



### NOTES:

- A. DIMENSIONS ARE IN MILLIMETERS.
- B. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- C. DRAWING FILENAME: UMLP10Arev2

### Figure 17. 10-Lead, Ultrathin Molded Leadless Package (UMLP)

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**BOTTOM VIEW** 





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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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Rev. 144

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